

B2526 PCB STACKUP

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Recommended B2526 PCB Stackup (2 Signal Layers and 4 Power Planes)

Layer	Artwork	Layer Name	Material Type	Dielectric Thickness (mils)	Trace Width (mils)	Cu Thickness (mils)	Dielectric Constant	Controlled Impedance (Ohms)	Description	
1	artwork_1	Top_Signal_1	Conductive		7	0.7		51	Microstrip	
			Dielectric	5			4.7		Core/Pre-preg	
2	artwork_2	GROUND	Conductive			1.4			Plane	Power_Pair_1
			Dielectric	5			4.7		Core/Pre-preg	
3	artwork_3	P2V5/P1V8	Conductive			1.4			Plane	Power_Pair_1
			Dielectric	30			4.7		Core/Pre-preg	
4	artwork_4	P3V3	Conductive			1.4			Plane	Power_Pair_2
			Dielectric	5			4.7		Core/Pre-preg	
5	artwork_5	GROUND	Conductive			1.4			Plane	Power_Pair_2
			Dielectric	5			4.7		Core/Pre-preg	
6	artwork_12	Bot_Signal_2	Conductive		7	0.7	4.7	51	Microstrip	

Notes:

- (1) Total board thickness: 0.062 +/- 0.01 inch
- (2) Differential pair (Trace_width/Trace_gap = 7/7 mils) impedance should be controlled at 100 ohms +/- 10%
- (3) Manufacturer has a right to make a layer thickness adjustment to make the differential impedance equal to 100 ohms +/- 10%.
- (4) Differential trace_width/Trace_gap = 7/7 mils
- (5) Each power pair planes (layer2/layer3, layer4/layer5) should stack as closer as possible, so it can make maximum capacitance for decoupling